

I claim:

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a,
1. A method for producing an electrical connection between integrated circuits, which comprises:

providing a first integrated circuit having a terminal, a signal terminal;

forming an electrically conductive connection between the terminal and the signal terminal of the first integrated circuit;

providing a second integrated circuit having a terminal that is coupled to a protective structure for protecting against electrostatic discharges;

disposing the first and second integrated circuits adjacent one another;

electrically connecting the signal terminal of the first integrated circuit to the terminal of the second integrated circuit; and

severing the electrically conductive connection between the terminal and the signal terminal of the first integrated circuit using an energy pulse.

2. The method according to claim 1, wherein the severing step is performed by applying an electrical current pulse to the terminal of the second integrated circuit.

3. The method according to claim 1, wherein the forming step includes:

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forming the electrically conductive connection with a portion of reduced cross sectional area as compared to the rest of the connection; and

dimensioning the portion to dissipate electrostatic discharges between the terminal and the signal terminal of the first integrated circuit and to be severed during application of the energy pulse in the severing step.

4. The method according to claim 3, wherein the energy pulse used in the severing step is an electrical current pulse applied to the terminal of the second integrated circuit.

5. The method according to claim 1, including:

disposing the first and second integrated circuits in a package having terminal pins so that the signal terminal of the first integrated circuit is not accessible from outside of the package; and

connecting the terminal of the first integrated circuit and the terminal of the second integrated circuit to a respective terminal pin of the package.

6. The method according to claim 5, wherein the severing step is performed after the step of connecting the respective terminals to the respective terminal pins.

7. The method according to claim 1, wherein the disposing step is performed so that terminal of the second integrated circuit is not covered by the first integrated circuit.

8. A method for producing an electrical connection between integrated circuits, which comprises:

providing a first integrated circuit having a surface;

disposing first and second terminal pads on the surface of the first integrated circuit;

forming an electrically conductive connection between the first and second terminal pads of the first integrated circuit;

providing a second integrated circuit having a surface;

disposing first and second terminal pads on the surface of the second integrated circuit;

electrically coupling at least the first terminal pad of the second integrated circuit to a protective structure for protecting against electrostatic discharges;

disposing the surfaces of the first and second integrated circuits longitudinally adjacent one another so that the first and second terminal pads of the second integrated circuit are not covered by the first integrated circuit;

electrically joining at least one of the first and second terminal pads of the first integrated circuit to one of the first and second terminal pads of the second integrated circuit;

forming an electrically conductive connection between the first and second terminal pads of the first integrated circuit; and

severing the electrically conductive connection using an energy pulse.

9. The method according to claim 8, wherein the electrically joining step is performed using an electrically conductive solderable material.

10. The method according to claim 8, wherein the electrically joining step is performed using a conductive adhesive material.

11. The method according to claim 8, including electrically joining the other one of the first and second terminal pads of the first integrated circuit to the other one of the first and second terminal pads of the second integrated circuit.

12. An arrangement of electrically connected integrated circuits, comprising:

a first integrated circuit including a terminal, a signal terminal, and an connection electrically connecting the terminal and the signal terminal, said connection including a main portion having a cross sectional area, and said connection including a constricted portion having a reduced cross sectional area with respect to said cross sectional area of said main portion; and

a second integrated circuit including a terminal having a protective structure for protecting against electrostatic

discharge, and a connection electrically connecting said terminal of said second integrated circuit to said signal terminal of said first integrated circuit.

13. The arrangement according to claim 12, wherein said constricted portion is dimensioned to conduct electrostatic charges and dimensioned for severance when subjected to an energy pulse.

14. The arrangement according to claim 12, wherein:

said first integrated circuit includes at least one further signal terminal; and

said connection electrically connecting said terminal of said second integrated circuit to said signal terminal of said first integrated circuit includes a diode, and said connection electrically connecting said terminal of said second integrated circuit to said signal terminal of said first integrated circuit includes a further diode electrically connecting said at least one further signal terminal to said terminal of said second integrated circuit.